

Chips shortage, the European response: EU Chips Act

Marco Ceccarelli DG-CNECT - European Commission World Manufacturing Forum 25 November 2022



Global semiconductor crisis Impact on industries

Increasing demand

- Accelerated digital transition
- Increased demand for semiconductors fueling severe shortage

Fragile supply chain

 Not resilient to disruptions such as COVID-19 pandemic



- **Concentration of production** in Asia (Taiwan, Korea) and high entry costs
- Geopolitical tensions (e.g. South China Sea, export control measures)

Detrimental effects across industries



Example: Automotive

- 11 million less cars produced in 2021, \$210B lost revenues
- -33% car sales in Europe







Chip demand growth



Doubling of demand: Market to exceed USD 1 Trillion before by 2030

Emerging market opportunities: Al, edge computing, digital transformation



Technological changes: miniaturisation limits



Digital Decade Target: **Double EU share** in global **semiconductor production** to **20% by 2030**







EU investments in manufacturing capacity

- Global investments in capacity grew 3x in 10 years
- EU industry **spending** did not increase (now ~4%)
- EU's share of capacity kept declining over the past 20 years (now ~7%)



Full dependency => risks for European sovereignty, security and economy

- Production is capital-intensive with major upfront investments; risk offset needed
- Semiconductors is of **key strategic value** with wide impact: main economies designed important incentive measures



The context justifies use of TFEU art 107.3c - aid to facilitate economic activities of common interest







The EU Chips Act

- We will present a European Chips Act... This is not just a matter of our competitiveness. This is also a matter of **tech sovereignty**. – Commission President Ursula von der Leyen

Vision

To jointly create a state-of-the-art European chip ecosystem, that includes world-class research, design and production capacities

Key objectives

- strengthen research and technology leadership
- build and reinforce its innovation capacity in design, manufacturing and packaging
- put in place framework to increase substantially production capacity by 2030
- address the acute **skills** shortage, attract new talent
- · develop mechanism to monitor supply chain and intervene if needed









Chips Act – State of play

Council

- Discussions ongoing in parallel Industry CWP and Research CWP
- CZ chairs working towards a parallel timeline and alignment
- Adoption of <u>general approach</u> expected December 1st

Parliament

- 6 Parliamentary Committees involved, ITRE in the lead: draft opinions published
- Votes scheduled Nov-Jan
- Plenary vote planned for Feb 2023











Three pillars of the Chips Act

European Semiconductor Board (Governance)

Pillar 1

Chips for Europe Initiative

- Initiative on infrastructure building in synergy with the EU's research programmes
- Support to start-ups and SMEs

Pillar 2

Security of SupplyFirst-of-a-kind

semiconductor production facilities

Pillar 3

Monitoring and Crisis Response

- Monitoring and alerting
- Crisis coordination mechanism with MS
- Strong Commission
 powers in times of crisis







Pillar 1 - Chips for Europe Initiative Bridging the gap from lab to fab

Create *large innovation capacity* and *a resilient and dynamic* semiconductor *ecosystem*

Objectives

- 1. Build a virtual platform to reinforce Europe's design capacity
- 2. Enhance existing and developing new **pilot lines**
- 3. Accelerate the development of quantum chips
- 4. Create a network of competence centres across Europe
- 5. Establish a **Chips Fund** to facilitate access to **loans and equity** by start-ups, scale-ups and SMEs in the value chain

Pilot lines

Chips JU



Pillar 2 - Security of supply and resilience State aid for Manufacturing facilities

Integrated Production Facility (IPF)

First-of-a-kind facility which produces the chips (mostly) for the same undertaking

Open EU Foundry (OEF)

First-of-a-kind facility that produces chips (mostly) for unrelated undertakings

First-of-a-kind facility: to qualify, facility needs to offer innovation in terms of products or process that is not yet present in the Union (not to distort competition)

Conditions: positive impact, security of supply and commitment to next generation

Relevant projects have been announced already by Intel, Infineon, ST-Microelectronics and GlobalFoundries







Pillar 2 – Security of supply and resilience First of a Kind facilities: what qualifies

The main stages of semiconductor production may be eligible









Pillar 3: Monitoring and crisis response



Pillar 3: Monitoring and crisis response International partnerships

- Semiconductor value chain is global and spread over different world regions
- We need to cooperate with like-minded partner countries, proactively managing interdependencies to ensure
 - a reliable global marketplace for European products, and
 - security of supply, including in crisis situations.

EU-US Trade and Technology Council

- coordinate measures to secure supply of semiconductors
- joint actions to exchange information and to coordinate on:
 - Early warning systems to detect supply issues
 - Industry-led methods to estimate demand
 - avoid subsidy races
 - Improve understanding of global demand

Further: Digital Partnerships with Asian countries









Pillar 3: Monitoring and crisis response European survey – companies' engagement



WIN-WIN

- Suppliers/users help the EU Semiconductors Board have a better understanding of the supply chain
- The ensuing report should also be a valuable source of information, as regards to the resilience of the supply chain, for the respondents themselves



Aggregate results (not tracing back to individual companies) will allow

- Identifying structural weaknesses in the European semiconductor value chain
- Exploring potential early warning indicators
- Defining a first approach towards a monitoring mechanism







Access to the consultation



More information

<u>https://digital-</u> <u>strategy.ec.europa.eu/en/consultations/euro</u> <u>pean-semiconductor-value-chain-</u> <u>consultation</u>









Thank you

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Microelectronics and Photonics Industry

DG CNECT – European Commission





